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The Numerical Challenges in Multiphysical Modeling of Laser Welding with ALE

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INTRODUCTION: The present work summarizes the numerical challenges in creation and validation of freesurface models using ALE moving mesh coupled with heat transfer equation and Navier-Stokes fluid flow. The influence of a set of numerical parameters as well as physical hypotheses on the dynamics of the keyhole and the characteristics of the melt formed in titanium alloy Ti-6Al-4V is analyzed.

COMPUTATIONAL METHODS:

RESULTS: Optimal parameters allow to reproduce the whole lifetime of the keyhole during pulsed welding of Ti6Al4V alloy (temperature field + velocity field).





Heat transfer

- time-dependent
- standalone laser pulse
- T-dependent absorption coefficient



Figure 1. Nd:YAG laser pulse of 6 ms, 1.5 kW, $Ø = 560 \mu m$, $\eta_{solid} = 200 Pa \cdot s$.

Influence of critical parameters:

Avoid low solid viscosity

Relaxation of solidified ring

Relaxation of MZ center

- Parasite velocities in solid
- Less profound keyhole
- Unphysical relaxation of solid

Red profile - end of solidification Wireframe – end of cooling

 $A = A_{solid} + (A_{liauid} - A_{solid}) \cdot flc2hs(T - T_m, \Delta T),$

 $A_{liquid} = A_{surf} + (A_{kh} - A_{surf}) \cdot flc2hs(T - T_{v}, \Delta T),$

Newtonian liquid **Navier-Stokes** Mean viscosity in solid phase Inconsistent stabilization

$$o\left|\frac{\partial \vec{U}}{\partial t} + \left(\vec{U} \cdot \vec{\nabla}\right)\vec{U}\right| = \vec{\nabla} \cdot \left[-pI + \eta(T)\left(\vec{U} \cdot \vec{\nabla} + \left(\vec{U} \cdot \vec{\nabla}\right)^{\dagger}\right)\right] + \vec{F}$$

 $\eta(T) = \eta_{solid} + (\eta_{liquid} - \eta_{solid}) flc2hs(T-T_m, \Delta T).$ natural convection (Boussinesq approximation), • surface tension force / Marangoni convection • recoil pressure in the keyhole

 $p_r = \frac{(1+\beta)}{2} \cdot a \cdot e^{-\frac{b}{T}+c}$

•Hyperelastic smoothing is better



Figure 2. Unphysical relaxation of solidified weld between the end of solidification and the end of cooling for different solid viscosities.



Figure 3. The influence of solid viscosity on the evolution of maximal temperature, melt velocity and keyhole depth for standalone Nd:YAG laser pulse on Ti-6Al-4V plate (6 ms, 1.5 kW, \emptyset = 560 μ m).

A_{KH}>0.8

Convergence problems

Important undershoots of pressure and stress accumulation around the impact zone



 $\nabla \cdot U = 0$

Deformation driven by velocity field

Parametric studies :

- •ALE smoothing methods
- •Numerical stabilization of N-S equation
- <u>Solid</u> and liquid viscosity
- •Adsorption in the keyhole A _{кн}
- Condensation coefficient β
- Incompressible VS weakly compressible N-S



CONCLUSIONS:

- Convergence problems associated with too important deformation of free surface (remeshing?)
- Keyhole depth sensitive to : solid and liquid viscosity, keyhole adsorption coefficient and condensation coefficient
- Acceptable mass conservation